SGS-THOMSON MICROELECTRONICS

MK41H87(N)-25/35/45

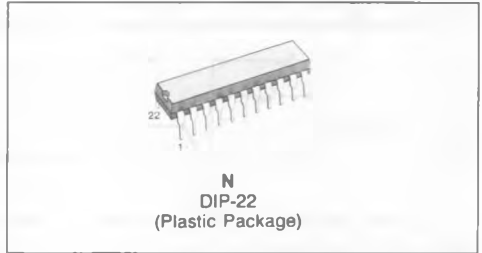## 64K × 1 CMOS STATIC RAM

- 25, 35, AND 45 NS ADDRESS ACCESS TIME

- EQUAL ACCESS AND CYCLE TIMES

- 22-PIN, 300 MIL PLASTIC DIP

- ALL INPUTS AND OUTPUTS TTL COMPATIBLE, LOW CAPACITANCE, AND PROTECTED AGAINST STATIC DISCHARGE

- JEDEC STANDARD PINOUT

N
DIP-22
(Plastic Package)

MK41H87 TRUTH TABLE

$\overline{CE}$	$\overline{WE}$	Mode	Q	Power
H	X	Deselect	High Z	Standby
L	L	Write	High Z	Active
L	H	Read	Data Out	Active

DESCRIPTION

The MK41H87 features fully static operation requiring no external clocks or timing strobes, and equal address access and cycle times. The MK41H87 requires only a single +5V ± 10 percent power supply, and it is fully TTL compatible.
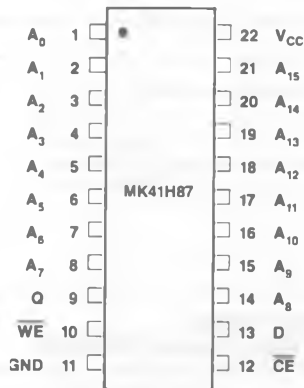
The MK41H87 has a Chip Enable power down feature which automatically reduces power dissipation when the $\overline{CE}$ pin is brought inactive (high). Standby Power can be further reduced by holding the Address and $\overline{CE}$ pins at full supply rail voltages.

OPERATIONS

READ MODE

The MK41H87 is in the Read Mode whenever $\overline{WE}$ (Write Enable) is high and $\overline{CE}$ (Chip Enable) is low, providing a ripple-through access to data from one of 65,536 locations in the static storage array. Valid data will be available at the Data Output pin (Q) within t_{AA} after the last address input signal is stable, providing that the $\overline{CE}$ access time is satisfied. If $\overline{CE}$ access time is not met, data access will be measured from the limiting parameter (t_{CA}) rather

FIGURE 1. PIN CONNECTIONS

A_0	1		22	V_{CC}
A_1	2		21	A_{15}
A_2	3		20	A_{14}
A_3	4		19	A_{13}
A_4	5		18	A_{12}
A_5	6	MK41H87	17	A_{11}
A_6	7		16	A_{10}
A_7	8		15	A_9
Q	9		14	A_8
$\overline{WE}$	10		13	D
GND	11		12	$\overline{CE}$

PIN NAMES

A_0 - A_{15} - Address	V_{CC} - + 5 volts
$\overline{CE}$ - Chip Enable	D - Data In
$\overline{WE}$ - Write Enable	Q - Data Out
GND - Ground	

than the address. The state of the Data Output pin is controlled by the $\overline{CE}$ and $\overline{WE}$ control signals. The Q may be in an indeterminate state at t_{CL}, but the Q will always have valid data at t_{AA}.

FIGURE 2. READ-READ-READ-WRITE TIMING
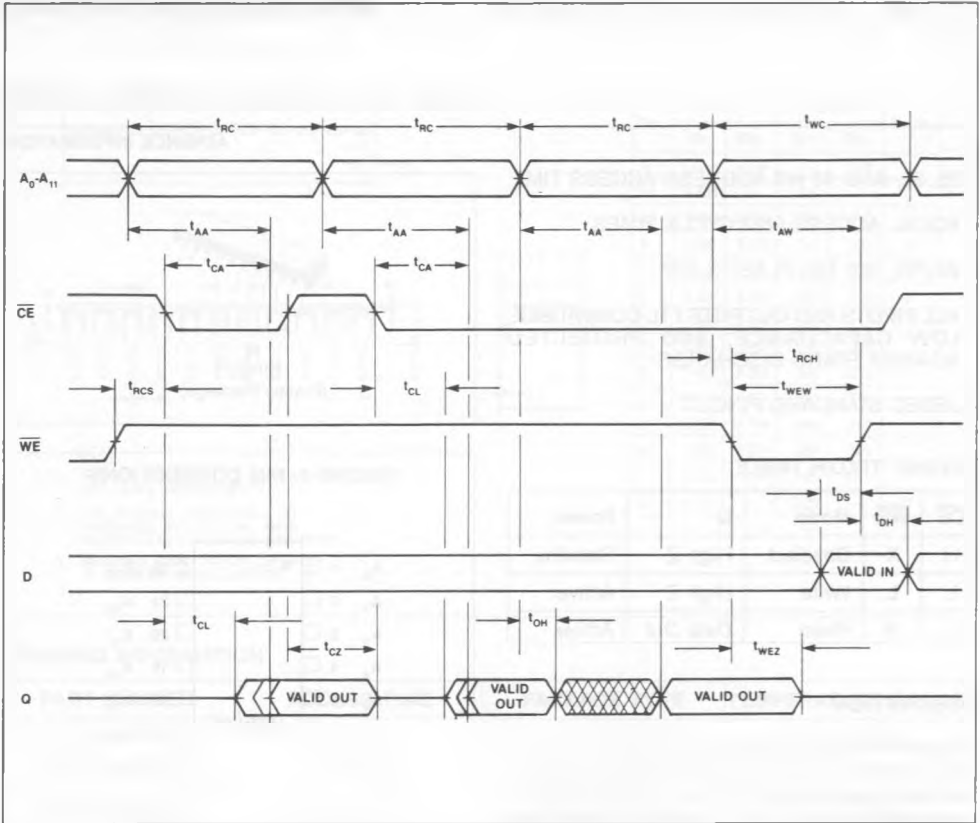
READ CYCLE TIMING
AC ELECTRICAL CHARACTERISTICS
$(0°C \leq T_A \leq 70°C)$ $(V_{CC} = 5.0$ V $\pm$ 10 percent)

SYM	PARAMETER	MK41H87-25		MK41H87-35		MK41H87-45		UNITS	NOTES
		MIN	MAX	MIN	MAX	MIN	MAX		
t_{RC}	Read Cycle Time	25		35		45		ns	
t_{AA}	Address Access Time		25		35		45	ns	1
t_{CL}	Chip Enable to Low-Z	5		5		5		ns	2
t_{CA}	Chip Enable Access Time		25		35		45	ns	1
t_{RCS}	Read Command Setup Time	0		0		0		ns	
t_{RCH}	Read Command Hold Time	0		0		0		ns	
t_{OH}	Valid Data Out Hold Time	3		3		3		ns	1
t_{CZ}	Chip Enable to High-Z		10		12		15	ns	2
t_{WEZ}	Write Enable to High-Z		12		14		17	ns	2

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MICROELECTRONICS

WRITE MODE

The MK41H87 is in the Write Mode whenever the $\overline{WE}$ and $\overline{CE}$ inputs are in the low state. $\overline{CE}$ or $\overline{WE}$ must be high during address transitions. Addresses must be held valid throughout a write cycle. The Write begins with the concurrence of a low on $\overline{WE}$ and $\overline{CE}$. Therefore, t_{AS} is referenced to the latter occurring edge of $\overline{CE}$ or $\overline{WE}$. If the output is enabled ($\overline{CE}$ is low), then $\overline{WE}$ will return the output to high impedance within t_{WEZ} of its falling edge. Data-In must remain valid t_{DH} after the rising edge of $\overline{CE}$ or $\overline{WE}$.

FIGURE 3. WRITE-WRITE-WRITE-READ TIMING
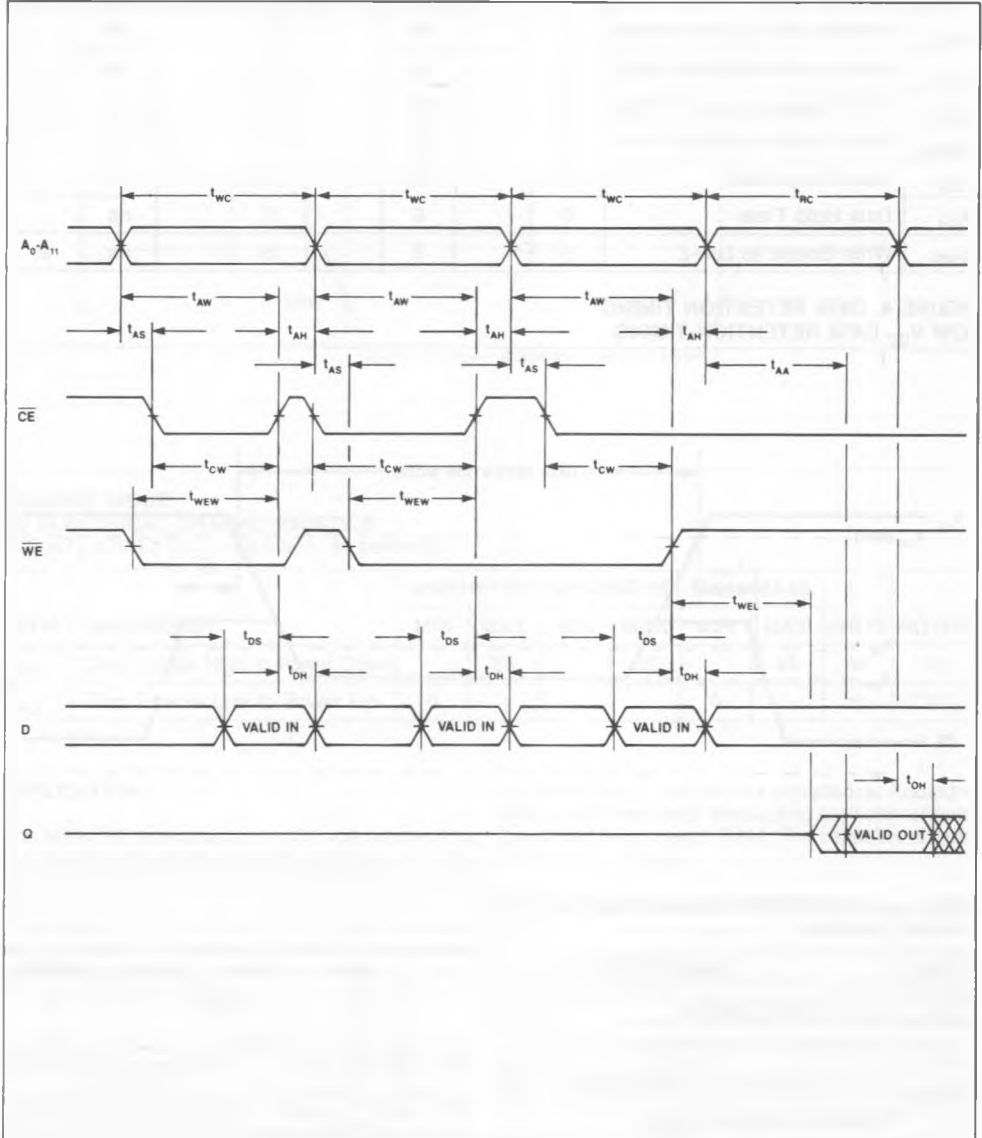
WRITE CYCLE TIMING
AC ELECTRICAL CHARACTERISTICS
(0°C ≤ T$_A$ ≤ 70°C) (V$_{CC}$ = 5.0 V ± 10 percent)

SYM	PARAMETER	MK41H87-25		MK41H87-35		MK41H87-45		UNITS	NOTES
		MIN	MAX	MIN	MAX	MIN	MAX		
t$_{WC}$	Write Cycle Time	25		35		45		ns	
t$_{AS}$	Address Setup Time	0		0		0		ns	
t$_{AW}$	Address Valid to End of Write	20		30		40		ns	
t$_{AH}$	Address Hold after End of Write	0		0		0		ns	
t$_{CW}$	Chip Enable to End of Write	20		30		40		ns	
t$_{WEW}$	Write Enable to End of Write	20		25		30		ns	
t$_{DS}$	Data Setup Time	20		25		35		ns	
t$_{DH}$	Data Hold Time	0		0		0		ns	
t$_{WEL}$	Write Enable to Low-Z	5		5		5		ns	2

FIGURE 4. DATA RETENTION TIMING
LOW V$_{CC}$ DATA RETENTION TIMING
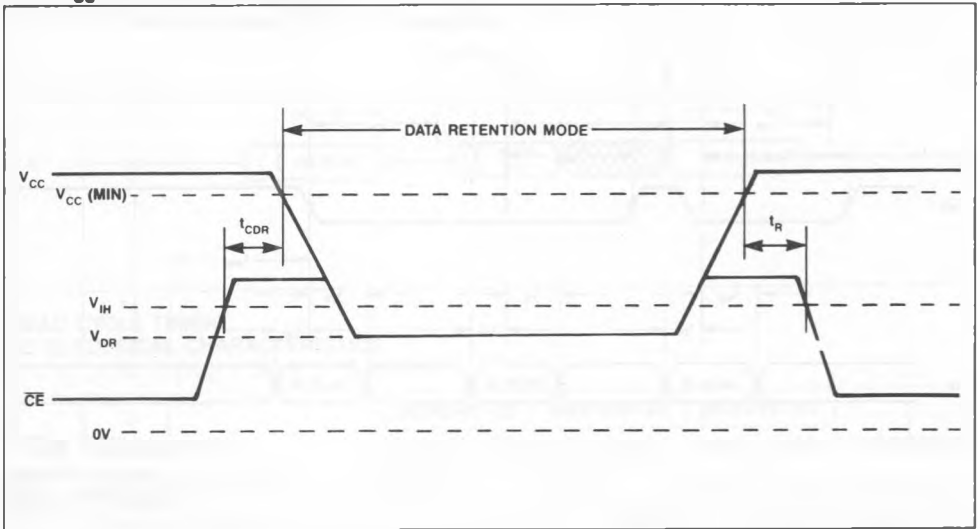
LOW V$_{CC}$ DATA RETENTION CHARACTERISTICS
(0°C ≤ T$_A$ ≤ 70°C)

SYM	PARAMETERS	MIN	MAX	UNIT	NOTES
V$_{DR}$	V$_{CC}$ for Data Retention	2.0	V$_{CC}$ (min)	V	6
I$_{CCDR}$	Data Retention Power Supply Current	—	500	μA	6
t$_{CDR}$	Chip Deselection to Data Retention Time	0	—	ns	
t$_R$	Operation Recovery Time	t$_{RC}$	—	ns	

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STANDBY MODE

The MK41H87 is in Standby Mode whenever $\overline{CE}$ is held at or above V_{IH}.

FIGURE 5. STANDBY MODE TIMING
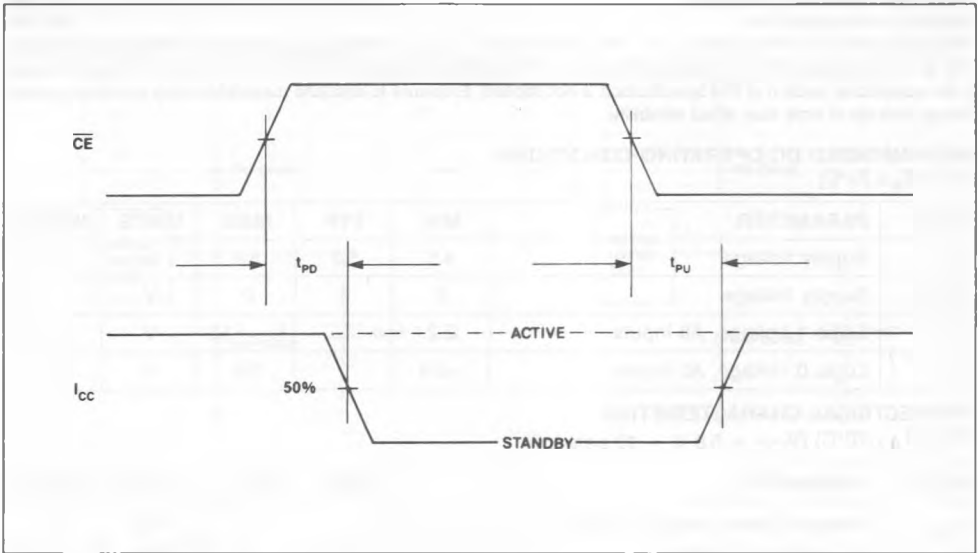
STANDBY MODE
AC ELECTRICAL CHARACTERISTICS
$(0°C \leq T_A \leq 70°C)$ (V_{CC} = 5.0 V ± 10 percent)

SYM	PARAMETER	MK41H87-25		MK41H87-35		MK41H87-45		UNITS	NOTES
		MIN	MAX	MIN	MAX	MIN	MAX		
t_{PD}	Chip Enable High to Power Down		25		35		45	ns	10
t_{PU}	Chip Enable Low to Power Up	0		0		0		ns	10

APPLICATION

The MK41H87 operates from a 5.0 volt supply. It is compatible with all standard TTL families on all inputs and outputs. The device should share a solid ground plane with any other devices interfaced with it, particularly TTL devices. Additionally, because the outputs can drive rail-to-rail into high impedance loads, the 41H87 can also interface to 5 volt CMOS on all inputs and outputs.

Since very high frequency current transients will be associated with the operation of the MK41H87, power line inductance must be minimized on the circuit board power distribution network. Power and ground trace gridding or separate power planes can be employed to reduce line inductance. Additionally, a high frequency decoupling capacitor should be placed next to each RAM. The capacitor should be 0.1 μF or larger.

Though often times not thought of as such, the traces on a memory board are basically unterminated, low impedance transmission lines. As such they are subject to signal reflections manifested as noise, undershoots and excessive ringing. Series termination in close proximity to the TTL drivers can improve driver/signal path impedance matching. While experimentation most often proves to be the only practical approach to selection of series resistors, values in the range of 10 to 33 ohms often prove most suitable.

ABSOLUTE MAXIMUM RATINGS*

Voltage on any pin relative to GND . . . . −1.0 V to +7.0 V
Ambient Operating Temperature (T_A) . . . . 0°C to +70°C
Ambient Storage Temperature (Plastic) . . . . −55°C to +125°C
Ambient Storage Temperature (Ceramic) . . . . −65°C to +150°C
Total Device Power Dissipation . . . . 1 Watt
Output Current per Pin . . . . 50 mA

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS
(0°C ≤ T_A ≤ 70°C)

SYM	PARAMETER	MIN	TYP	MAX	UNITS	NOTES
V_{CC}	Supply Voltage	4.5	5.0	5.5	V	3
GND	Supply Voltage	0	0	0	V	
V_{IH}	Logic 1 Voltage, All Inputs	2.2		V_{CC}+1.0	V	3
V_{IL}	Logic 0 Voltage, All Inputs	−0.3		0.8	V	3

DC ELECTRICAL CHARACTERISTICS
(0°C ≤ T_A ≤ 70°C) (V_{CC} = 5.0 V ± 10 percent)

SYM	PARAMETER	MIN	MAX	UNITS	NOTES
I_{CC1}	Average Power Supply Current		70	mA	4
I_{CC2}	TTL Standby Current		8	mA	5
I_{CC3}	CMOS Standby Current		1.5	mA	6
I_{IL}	Input Leakage Current (Any Input Pin)	−1	+1	μA	7
I_{OL}	Output Leakage Current (Any Output Pin)	−10	+10	μA	8
V_{OH}	Output Logic 1 Voltage (I_{OUT} = −4 mA)	2.4		V	3
V_{OL}	Output Logic 0 Voltage (I_{OUT} = +8 mA)		0.4	V	3

CAPACITANCE
(T_A = 25°C, f = 1.0 MHz)

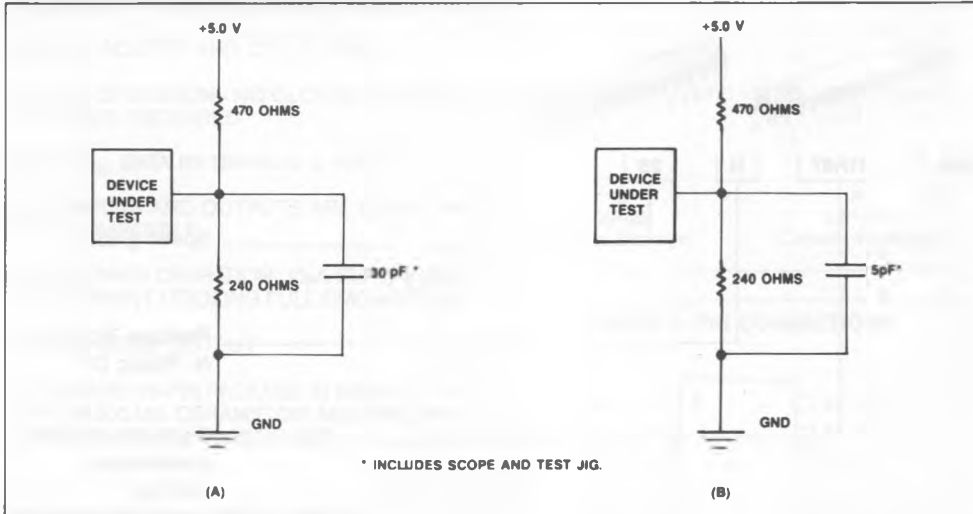| SYM	PARAMETER	TYP	MAX	UNITS	NOTES
C_1	Capacitance on input pins	4	5	pF	9
C_2	Capacitance on DQ pins	8	10	pF	5,9

NOTES
1. Measured with load shown in Figure 6(A).
2. Measured with load shown in Figure 6(B).
3. All voltages referenced to GND.
4. I_{CC1} is measured as the average AC current with V_{CC} = V_{CC} (max) and with the outputs open circuit. tcycle = min. duty cycle 100%.
5. $\overline{CE}$ = V_{IH}, All Other Inputs = Don't Care.
6. V_{CC} (max) ≥ $\overline{CE}$ ≥ V_{CC} − 0.3 V
   GND + 0.3 V ≥ A_0-A_{15} ≥ V_{IL} (min) or V_{IH} (max) ≥ A_0-A_{15} ≥ V_{CC} −0.3 V.
   All Other Inputs = Don't Care.

7. Input leakage current specifications are valid for all V_{IN} such that 0 V < V_{IN} < V_{CC}. Measured at V_{CC} = V_{CC} (max).
8. Output leakage current specifications are valid for all V_{OUT} such that 0 V < V_{OUT} < V_{CC}, $\overline{CE/CS}$ = V_{IH} and V_{CC} in valid operating range.
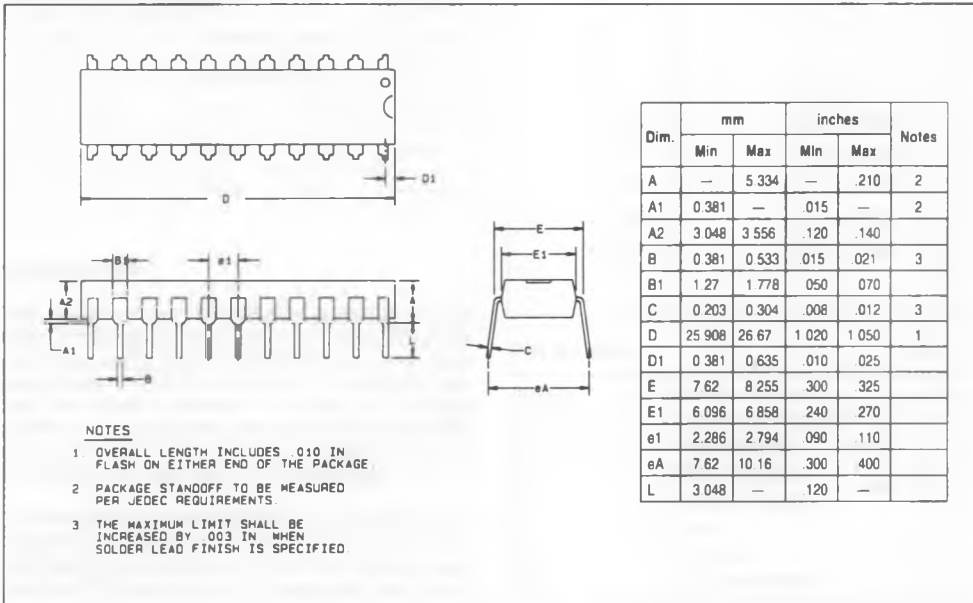9. Capacitances are sampled and not 100% tested.
10. Guaranteed, but not 100% tested.

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AC TEST CONDITIONS

Input Levels . . . . GND to 3.0 V
Transition Times . . . . .5 ns
Input and Output Signal Timing Reference Level . . . . .1.5 V
Ambient Temperature . . . . 0 °C to 70 °C
V_{CC} . . . . 5.0 V $\pm$ 10 percent

FIGURE 6. OUTPUT LOAD CIRCUITS

* INCLUDES SCOPE AND TEST JIG.

(A) (B)

22 PIN "N" PACKAGE

Dim.	mm		inches		Notes
	Min	Max	Min	Max	
A	—	5.334	—	.210	2
A1	0.381	—	.015	—	2
A2	3.048	3.556	.120	.140	
B	0.381	0.533	.015	.021	3
B1	1.27	1.778	.050	.070	
C	0.203	0.304	.008	.012	3
D	25.908	26.67	1.020	1.050	1
D1	0.381	0.635	.010	.025	
E	7.62	8.255	.300	.325	
E1	6.096	6.858	.240	.270	
e1	2.286	2.794	.090	.110	
eA	7.62	10.16	.300	.400	
L	3.048	—	.120	—	

NOTES

1. OVERALL LENGTH INCLUDES .010 IN FLASH ON EITHER END OF THE PACKAGE.

2. PACKAGE STANDOFF TO BE MEASURED PER JEDEC REQUIREMENTS.

3. THE MAXIMUM LIMIT SHALL BE INCREASED BY .003 IN WHEN SOLDER LEAD FINISH IS SPECIFIED.

ORDERING INFORMATION

PART NUMBER	ACCESS TIME	PACKAGE TYPE	TEMPERATURE RANGE
MK41H87N-25	25 ns	22 pin 300 mil Plastic DIP	0°C to 70°C
MK41H87N-35	35 ns	22 pin 300 mil Plastic DIP	0°C to 70°C
MK41H87N-45	45 ns	22 pin 300 mil Plastic DIP	0°C to 70°C

| MK | 41H87 | N | 25 |

Speed grade

Package Type
N: Plastic DIP

Device family and
identification
number

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prefix

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